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CENTRAL FAX CENTER****OCT 19 2007****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Applicant:	§	Art Unit:	2814
Ilya Karpov et al.	§		
Serial No.:	§	Examiner:	Long Pham
10/822,361	§		
Filed:	§	Docket:	ITL.0835D1US
April 12, 2004	§	P14730D	
For:	§	Assignee:	Intel Corporation
Fabricating Deeper and	§		
Shallower Trenches in	§	Conf. No.	3077
Semiconductor Structures	§		

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**SUPPLEMENTAL REPLY TO FINAL REJECTION**

Sir:

In further response to the final rejection mailed August 15, 2007, please amend the above-referenced patent application as follows:

Date of Deposit: October 19, 2007  
I hereby certify that this document is being facsimile transmitted to the United States Patent and Trademark Office (Fax No. 571/273-8300) on the date indicated above.  
*Cynthia L. Hayden*  
Cynthia L. Hayden